- **Organization . . . 4194304 × 32**
- **Single 5-V Power Supply (±10% Tolerance)**
- **72-Pin Single-In-Line Memory Module (SIMM) for Use With Sockets**
- **Utilizes Eight 16-Megabit DRAMs in Plastic Small-Outline J-Lead (SOJ) Packages**
- **Long Refresh Period 32 ms (2048 Cycles)**
- **All Inputs, Outputs, Clocks Fully TTL Compatible**
- **3-State Output**
- **Common $\overline{CAS}$ Control for Eight Common Data-In and Data-Out Lines in Four Blocks**
- **Enhanced Page Mode Operation With $\overline{CAS}$-Before-$\overline{RAS}$ (CBR), $\overline{RAS}$-Only, and Hidden Refresh**
- **Presence Detect**
- **Performance Ranges:**

	ACCESS TIME t_{RAC} (MAX)	ACCESS TIME t_{AA} (MAX)	ACCESS TIME t_{CAC} (MAX)	READ OR WRITE CYCLE (MIN)
'497BBK32-60	60 ns	30 ns	15 ns	110 ns
'497BBK32-70	70 ns	35 ns	18 ns	130 ns
'497BBK32-80	80 ns	40 ns	20 ns	150 ns

- **Low Power Dissipation**
- **Operating Free-Air-Temperature Range 0°C to 70°C**
- **Gold-Tabbed Version Available:† TM497BBK32**
- **Tin-Lead (Solder) Tabbed Version Available: TM497BBK32S**

description

The TM497BBK32 is a 16M-byte dynamic random-access memory (DRAM) organized as four times 4194304 × 8 in a 72-pin leadless single-in-line memory module (SIMM). The SIMM is composed of eight TMS417400DJ, 4194304 × 4-bit DRAMs, each in 24/26-lead plastic small-outline J-lead (SOJ) packages mounted on a substrate with decoupling capacitors. The TMS417400DJ is described in the TMS417400 data sheet.

The TM497BBK32 SIMM is available in the single-sided BK leadless module for use with sockets. The TM497BBK32 SIMM features $\overline{RAS}$ access times of 60 ns, 70 ns, and 80 ns. This device is characterized for operation from 0°C to 70°C.

operation

The TM497BBK32 operates as eight TMS417400DJs connected as shown in the functional block diagram and Table 1. The common I/O feature dictates the use of early write cycles to prevent contention on D and Q.

refresh

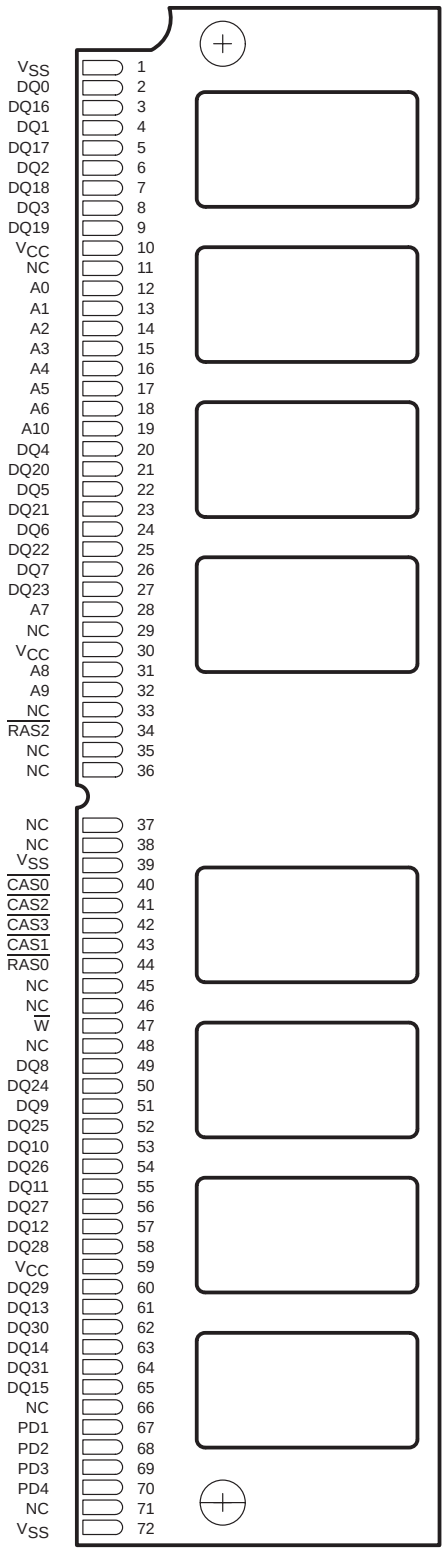
The refresh period is extended to 32 ms and, during this period, each of the 2048 rows must be strobed with $\overline{RAS}$ in order to retain data. $\overline{CAS}$ can remain high during the refresh sequence to conserve power.

power up

To achieve proper operation, an initial pause of 200 μs followed by a minimum of eight initialization cycles is required after full V_{CC} level is achieved. These eight initialization cycles need to include at least one refresh ($\overline{RAS}$-only or CBR) cycle.

† Part numbers in this data sheet are for the gold-tabbed version; the information applies to both gold-tabbed and solder-tabbed versions.

BK SINGLE-IN-LINE PACKAGE
(TOP VIEW)



(SIDE VIEW)

PIN NOMENCLATURE	
A0–A10	Address Inputs
CAS0–CAS3	Column-Address Strobe
DQ0–DQ31	Data In/Data Out
NC	No Connection
PD1–PD4	Presence Detects
RAS0, RAS2	Row-Address Strobe
V_{CC}	5-V Supply
V_{SS}	Ground
W	Write Enable

PRESENCE DETECT					
SIGNAL (PIN)		PD1 (67)	PD2 (68)	PD3 (69)	PD4 (70)
TM497BBK32	80 ns	V_{SS}	NC	NC	V_{SS}
	70 ns	V_{SS}	NC	V_{SS}	NC
	60 ns	V_{SS}	NC	NC	NC

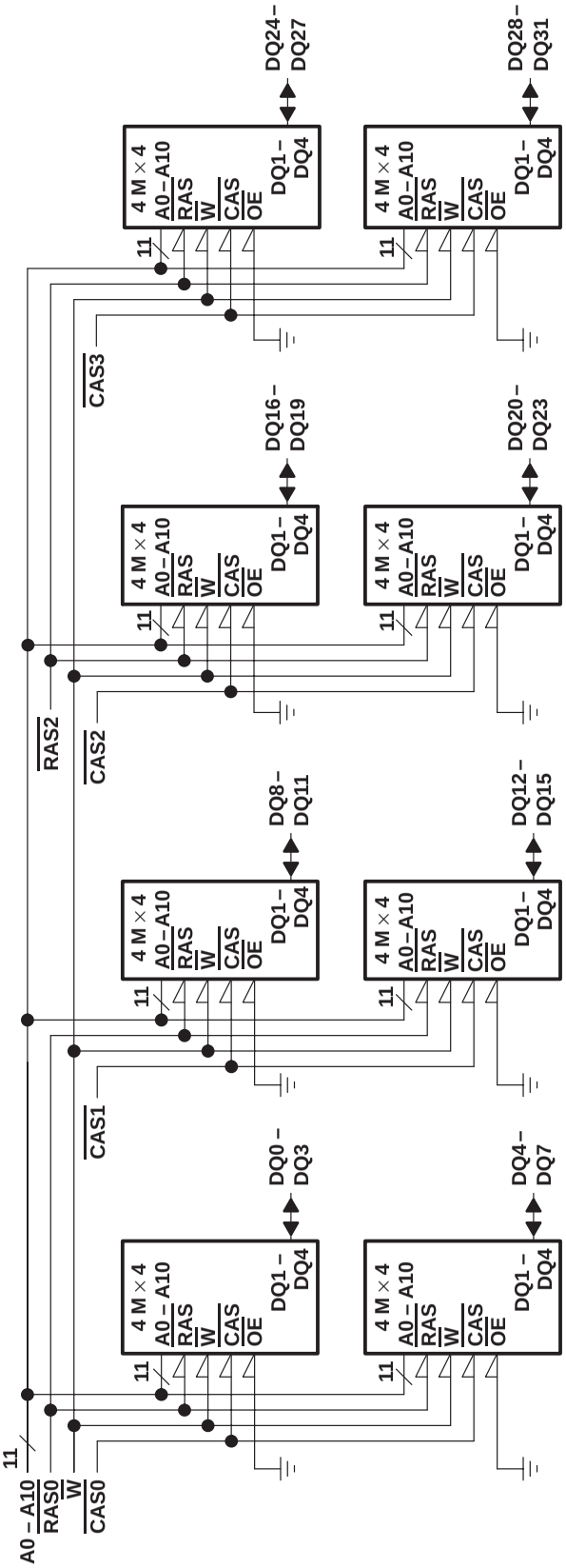
Table 1. Connection Table

DATA BLOCK	$\overline{\text{RASx}}$	$\overline{\text{CASx}}$
DQ0–DQ7	$\overline{\text{RAS0}}$	$\overline{\text{CAS0}}$
DQ8–DQ15	$\overline{\text{RAS0}}$	$\overline{\text{CAS1}}$
DQ16–DQ23	$\overline{\text{RAS2}}$	$\overline{\text{CAS2}}$
DQ24–DQ31	$\overline{\text{RAS2}}$	$\overline{\text{CAS3}}$

single-in-line memory module and components

PC substrate: 1,27 ± 0,1 mm (0.05 inch) nominal thickness; 0.005 inch/inch maximum warpage
Bypass capacitors: Multilayer ceramic
Contact area for TM497BBK32: Nickel plate and gold plate over copper
Contact area for TM497BBK32S: Nickel plate and tin-lead over copper

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1) . . . . . – 1 V to 7 V
Voltage range on any pin (see Note 1) . . . . . – 1 V to 7 V
Short-circuit output current . . . . . 50 mA
Power dissipation . . . . . 8 W
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . – 55°C to 125°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to V_{SS}.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2.4		6.5	V
V_{IL}	Low-level input voltage (see Note 2)	– 1		0.8	V
T_A	Operating free-air temperature	0		70	°C

NOTE 2: The algebraic convention, where the more negative (less positive) limit is designated as minimum, is used for logic-voltage levels only.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS‡	'497BBK32-60		'497BBK32-70		'497BBK32-80		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
V_{OH}	High-level output voltage	I_{OH} = – 5 mA	2.4		2.4		2.4		V
V_{OL}	Low-level output voltage	I_{OL} = 4.2 mA		0.4		0.4		0.4	V
I_I	Input current (leakage)	V_{CC} = 5.5 V, V_I = 0 V to 6.5 V, All others = 0 V to V_{CC}		± 80		± 80		± 80	µA
I_O	Output current (leakage)	$\overline{V_{CC}}$ = 5.5 V, V_O = 0 V to V_{CC}, $\overline{CAS}$ high		± 10		± 10		± 10	µA
I_{CC1}	Read- or write-cycle current (see Note 3)	V_{CC} = 5.5 V, Minimum cycle		880		800		720	mA
I_{CC2}	Standby current	V_{IH} = 2.4 V (TTL), After 1 memory cycle, $\overline{RAS}$ and $\overline{CAS}$ high		16		16		16	mA
		V_{IH} = V_{CC} – 0.2 V (CMOS), After 1 memory cycle, $\overline{RAS}$ and $\overline{CAS}$ high		8		8		8	mA
I_{CC3}	Average refresh current ($\overline{RAS}$ only or CBR) (see Note 3)	$\overline{V_{CC}}$ = 5.5 V, $\overline{RAS}$ cycling, ($\overline{RAS}$ only); $\overline{CAS}$ low (CBR)	Minimum cycle, $\overline{CAS}$ high $\overline{RAS}$ low after	880		800		720	mA
I_{CC4}	Average page current (see Note 4)	$\overline{V_{CC}}$ = 5.5 V, $\overline{RAS}$ low,	t_{PC} = MIN, $\overline{CAS}$ cycling	560		480		400	mA

‡ For test conditions shown as MIN/MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 3. Measured with a maximum of one address change while $\overline{RAS}$ = V_{IL}
4. Measured with a maximum of one address change while $\overline{CAS}$ = V_{IH}

capacitance over recommended ranges of supply voltage and operating free-air temperature, f = 1 MHz (see Note 5)

PARAMETER		MIN	MAX	UNIT
$C_{i(A)}$	Input capacitance, address inputs		40	pF
$C_{i(R)}$	Input capacitance, $\overline{RAS}$ inputs		28	pF
$C_{i(C)}$	Input capacitance, $\overline{CAS}$ inputs		14	pF
$C_{i(W)}$	Input capacitance, write-enable input		56	pF
$C_{o(DQ)}$	Output capacitance on DQ pins		7	pF

NOTE 5: V_{CC} = 5 V ± 0.5 V, and the bias on pins under test is 0 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		’497BBK32-60		’497BBK32-70		’497BBK32-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_{AA}	Access time from column address		30		35		40	ns
t_{CAC}	Access time from $\overline{CAS}$ low		15		18		20	ns
t_{CPA}	Access time from column precharge		35		40		45	ns
t_{RAC}	Access time from $\overline{RAS}$ low		60		70		80	ns
t_{CLZ}	$\overline{CAS}$ to output in low-impedance state	0		0		0		ns
t_{OH}	Output disable time from start of $\overline{CAS}$ high	3		3		3		ns
t_{OFF}	Output disable time after $\overline{CAS}$ high (see Note 6)	0	15	0	18	0	20	ns

NOTE 6: t_{OFF} is specified when the output is no longer driven.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

		’497BBK32-60		’497BBK32-70		’497BBK32-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_{RC}	Cycle time, random read or write (see Note 7)	110		130		150		ns
t_{PC}	Cycle time, page-mode read or write (see Notes 7 and 8)	40		45		50		ns
t_{RASP}	Pulse duration, page-mode, $\overline{RAS}$ low	60	100 000	70	100 000	80	100 000	ns
t_{RAS}	Pulse duration, non-page-mode, $\overline{RAS}$ low	60	10 000	70	10 000	80	10 000	ns
t_{CAS}	Pulse duration, $\overline{CAS}$ low	15	10 000	18	10 000	20	10 000	ns
t_{CP}	Pulse duration, $\overline{CAS}$ high	10		10		10		ns
t_{RP}	Pulse duration, $\overline{RAS}$ high (precharge)	40		50		60		ns
t_{WP}	Pulse duration, $\overline{W}$ low	10		10		10		ns
t_{ASC}	Setup time, column address before $\overline{CAS}$ low	0		0		0		ns
t_{ASR}	Setup time, row address before $\overline{RAS}$ low	0		0		0		ns
t_{DS}	Setup time, data before $\overline{CAS}$ low	0		0		0		ns
t_{RCS}	Setup time, $\overline{W}$ high before $\overline{CAS}$ low	0		0		0		ns
t_{CWL}	Setup time, $\overline{W}$-low before $\overline{CAS}$ high	15		18		20		ns
t_{RWL}	Setup time, $\overline{W}$-low before $\overline{RAS}$ high	15		18		20		ns
t_{WCS}	Setup time, $\overline{W}$-low before $\overline{CAS}$ low	0		0		0		ns
t_{WRP}	Setup time, $\overline{W}$-high before $\overline{RAS}$ low (CBR refresh only)	10		10		10		ns

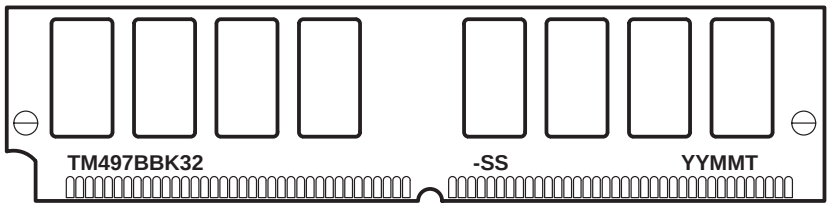
NOTES: 7. All cycles assume t_T = 5 ns.
8. To assure t_{PC} min, t_{ASC} should be ≥ t_{CP}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

		’497BBK32-60		’497BBK32-70		’497BBK32-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_{CAH}	Hold time, column address after $\overline{CAS}$ low	10		15		15		ns
t_{RHCP}	Hold time, $\overline{RAS}$ high from $\overline{CAS}$ precharge	35		40		45		ns
t_{DH}	Hold time, data after $\overline{CAS}$ low	10		15		15		ns
t_{RAH}	Hold time, row address after $\overline{RAS}$ low	10		10		10		ns
t_{RCH}	Hold time, $\overline{W}$ high after $\overline{CAS}$ high (see Note 9)	0		0		0		ns
t_{RRH}	Hold time, $\overline{W}$ high after $\overline{RAS}$ high (see Note 9)	0		0		0		ns
t_{WCH}	Hold time, $\overline{W}$ low after $\overline{CAS}$ low	10		15		15		ns
t_{WRH}	Hold time, $\overline{W}$ high after $\overline{RAS}$ low (CBR refresh only)	10		10		10		ns
t_{CHR}	Delay time, $\overline{RAS}$ low to $\overline{CAS}$ high (CBR refresh only)	10		10		10		ns
t_{CRP}	Delay time, $\overline{CAS}$ high to $\overline{RAS}$ low	5		5		5		ns
t_{CSH}	Delay time, $\overline{RAS}$ low to $\overline{CAS}$ high	60		70		80		ns
t_{CSR}	Delay time, $\overline{CAS}$ low to $\overline{RAS}$ low (CBR refresh only)	5		5		5		ns
t_{RAD}	Delay time, $\overline{RAS}$ low to column address (see Note 10)	15	30	15	35	15	40	ns
t_{RAL}	Delay time, column address to $\overline{RAS}$ high	30		35		40		ns
t_{CAL}	Delay time, column address to $\overline{CAS}$ high	30		35		40		ns
t_{RCD}	Delay time, $\overline{RAS}$ low to $\overline{CAS}$ low (see Note 10)	20	45	20	52	20	60	ns
t_{RPC}	Delay time, $\overline{RAS}$ high to $\overline{CAS}$ low (CBR only)	0		0		0		ns
t_{RSH}	Delay time, $\overline{CAS}$ low to $\overline{RAS}$ high	15		18		20		ns
t_{REF}	Refresh time interval		32		32		32	ms
t_T	Transition time	3	30	3	30	3	30	ns

9. Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.
10. The maximum value is specified only to assure access time.

device symbolization



YY = Year Code
MM = Month Code
T = Assembly Site Code
-SS = Speed Code

NOTE: The location of the part number may vary.

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